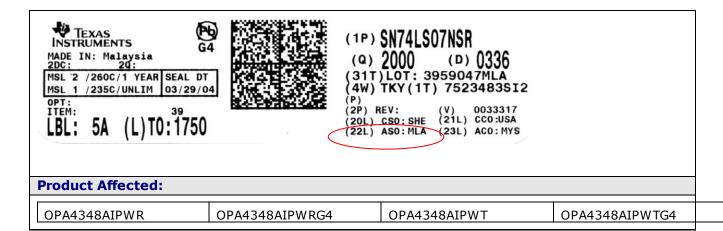
	2022081			-						
PCN Number:	PCN Date: August 19, 2022									
Title: Qualification of TI Malaysia as an additional assembly site for select Devices										
Customer Contact: PCN Manager Dept: Quality Services										
			7, 2022		Sample requests accepted until:			Sept 19, 20	)22*	
*Sample requests received after Sept 19, 2022 will not be supported.										
Change Type:			1							
Assembly Site			Design			<u> </u>		/afer Bump Site		
Assembly Process			☐ Data Sheet ☐ Part number change			<u> </u>		Wafer Bump Material		
Assembly Materials			Test Site	nange	H		Vafer Bump Process Vafer Fab Site			
<ul><li>☐ Mechanical Specification</li><li>☐ Packing/Shipping/Labeling</li></ul>			Test Process			H		Wafer Fab Materials		
Li Facking/Shipping/Labeling						Ħ		r Fab Proces		
			PCN	Deta	ils					
Description of Change:										
are as follows:	ssembly site for devices listed below in the product affected section. Construction differences re as follows:  Carsem TI Malaysia						1			
					_			<u> </u>	-	
	Mount Compound		SID#434165		4147858					
	Bond wire composition/diameter		Au, 1.0mil		Cu, 1.0mil					
Mold Cor	Mold Compound		SID#438518		4211471					
Reason for Change Supply continuity  Anticipated impa None		rm, Fit, Fu	nction, Q	uality	or Reliabili	ty (	positi	ve / negativ	ve):	
<b>Impact on Enviro</b>	nmental	Ratings								
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.										
RoHS		_	ACH		Green Status			IEC 62474		
No Change			inge 🔲		No Change			⊠ No Change		
<b>Changes to prod</b>	,									
Assembly Site	Assem	bly Site Ori (22L)	igin A	Assembly Country Code (23L)				Assembly City		
Carsem		CSZ			CHN			Jiangsu		
MLA	MLA MLA			MYS				Kuala Lumpur		
Sample product sh	nipping lat	oel (not ac	ctual prod	uct la	bel)					



TI Information Selective Disclosure

## Qualification Report Approve Date 24-JUNE -2022

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>OPA4348AIPWR</u>	QBS Reference: <u>INA1650QPWRQ1</u>	QBS Reference: <u>OPA356AQDBVRQ1</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	А3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/230/0 <sup>1</sup>
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/230/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	2/154/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	1/10/0
ESD	E2	ESD CDM	-	1000 Volts	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0
ESD	E2	ESD HBM	-	4000 Volts	-	1/3/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0
FTY	E6	Final Test Yield	-	-	1/1/0	-	-

- QBS: Qual By Similarity
- Qual Device OPA4348AIPWR is qualified at MSL2 260C

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail					
WW Change Management Team	PCN ww admin team@list.ti.com					

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